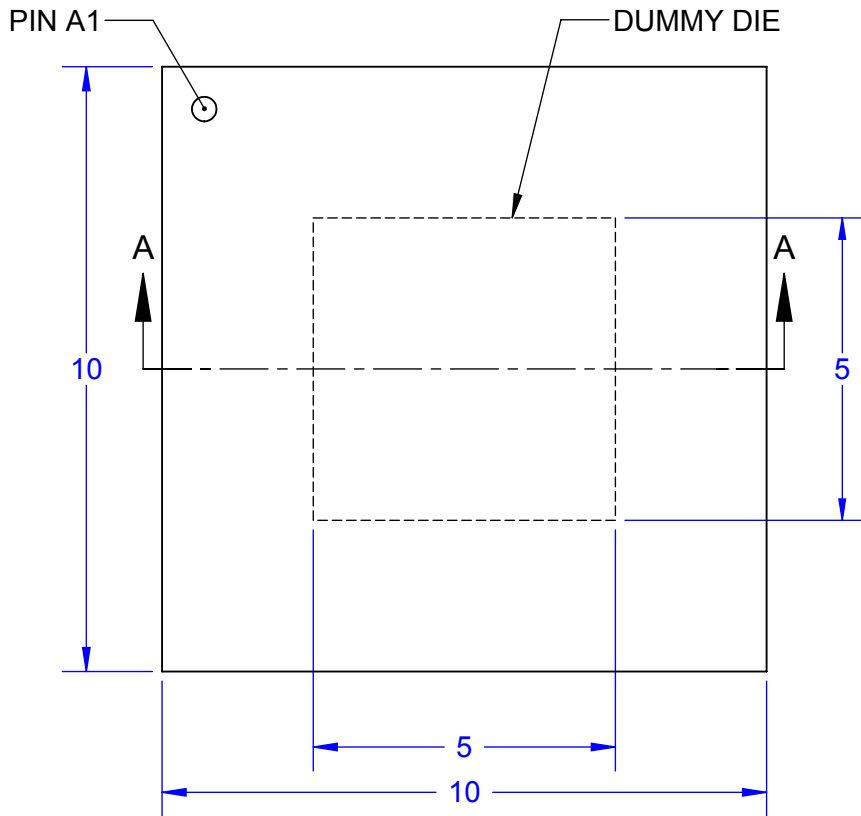
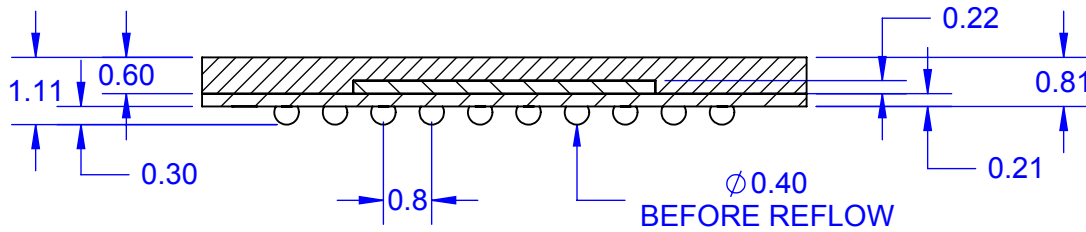
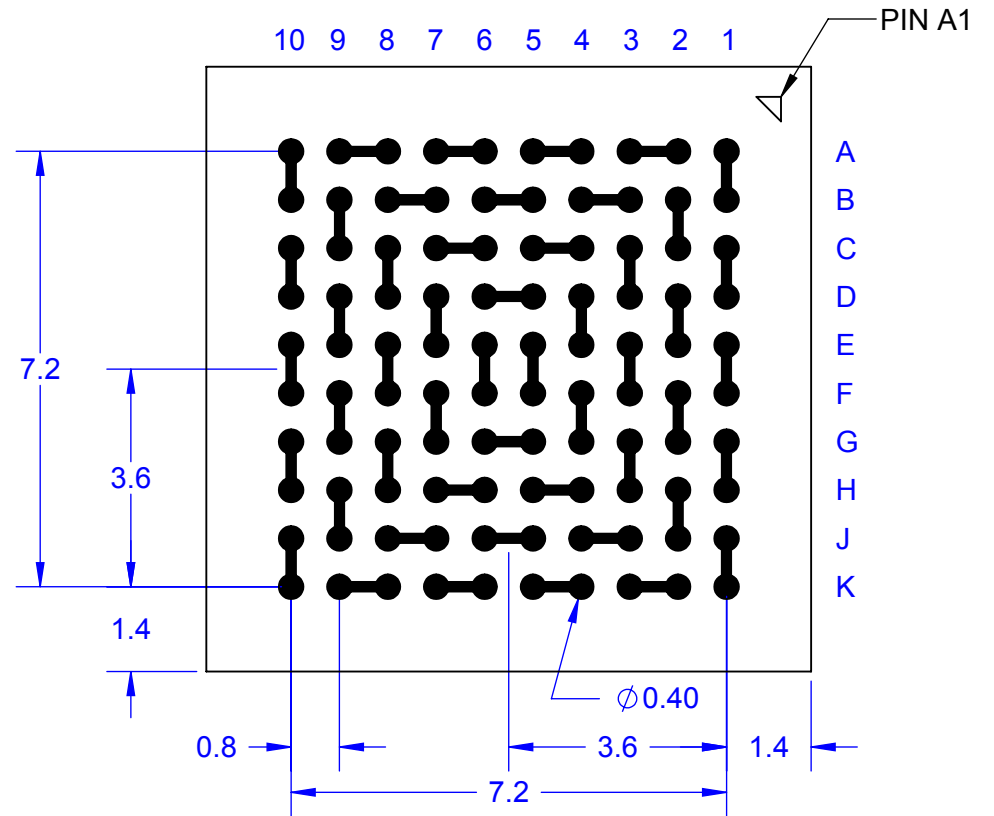


TOP VIEW



BALL VIEW




SECTION A-A

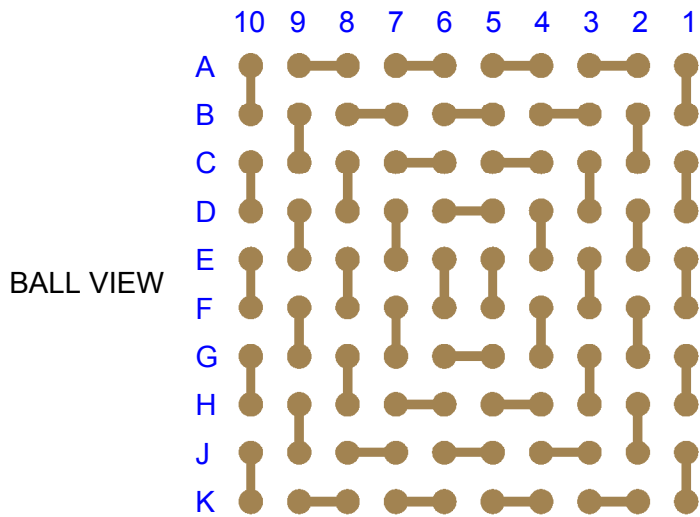
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.40mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.37mm [14.5 MIL].
- 5) PAD Cu DIAMETER: 0.406mm [16 MIL].
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE: 0.220mm [9 MIL] THICK.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

PART NUMBER TABLE

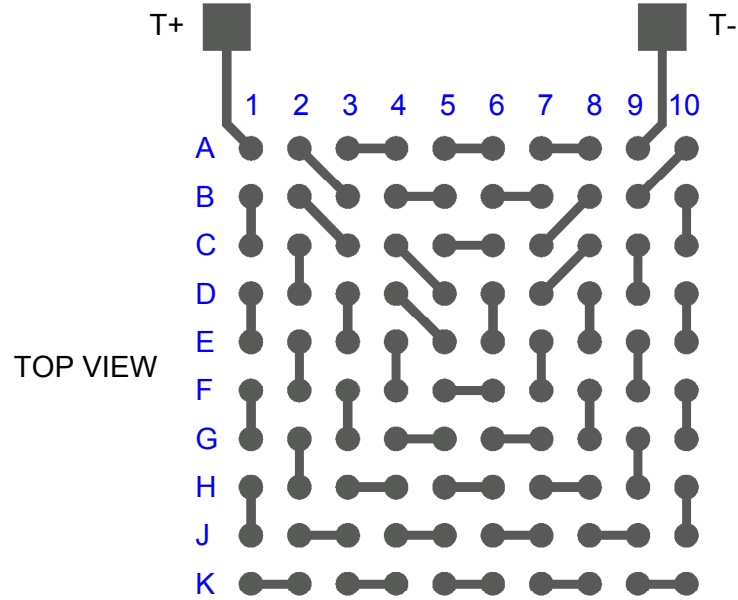
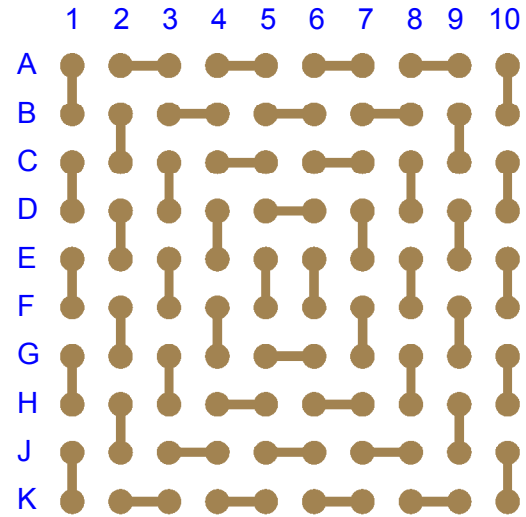
PART NUMER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA100T.8C-DC109D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
LGA100T.8G-DC109D	NONE	YES	YES	YES
BGA100T.8-DC109D	Sn63/Pb37	NO	NO	YES

APPROVALS	DATE				
DRAWN T.Au	04/21/14				
ENG M. Hart	04/21/14	TITLE BGA100T.8C-DC109D DAISY CHAIN DUMMY			
MFG		SCALE 8:1	SIZE A	DRAWING NO. 581090	REV A
QA		DO NOT SCALE DRAWING			SHEET 1 OF 2
CUST					
REVISED					



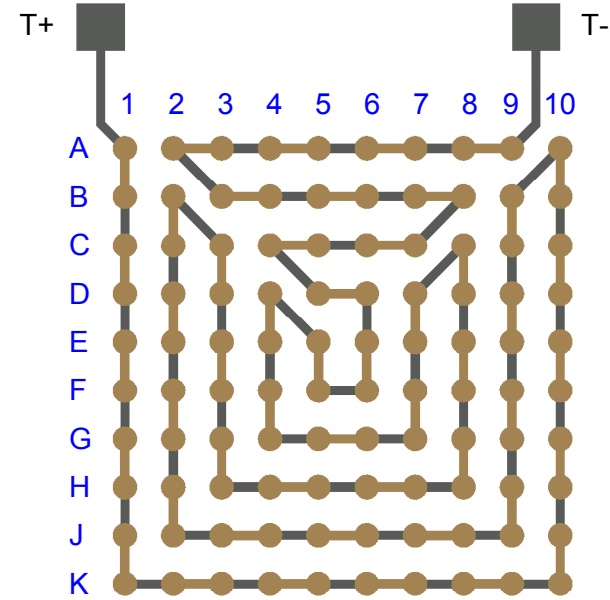
BALL VIEW

BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW

AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.406mm [16 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm [6 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.37mm [14.5 MIL].

TopLine[®]

TITLE				BGA100T.8C-DC109D DAISY CHAIN DUMMY			
SCALE	SIZE	DRAWING NO.	REV	SCALE	SIZE	DRAWING NO.	REV
8:1	A	581090	A	8:1	A	581090	A
DO NOT SCALE DRAWING						SHEET 2 OF 2	